



# TECHNICAL DATA SHEET

## Product Description

**AOS Non-Silicone Heat Sink Compound 370** was created developed over 35 years ago by AOS to solve the problems of contamination and migration associated with silicone-based products. The compound is a unique synthetic-based thermal grease used to insure quick, efficient heat transfer and dissipation. The primary advantage of this non-silicone product is long-term material stability. This means that the compound stays put and on the job over the full operable life of your hardware, exhibiting virtually no bleed or evaporation over a wide operating temperature range - even in a vacuum atmosphere ( $10^{-5}$  tor/mil, 24 hrs. @ 100°C). Compound will not leach, dry, harden, or melt in normal industrial use.

Silicone-based compounds have an undesirable tendency to physically migrate and contaminate components nearby. This interferes with circuit operation long after hardware installation to cause unexpected, untimely and often inaccessible problems. The AOS Heat Sink Compound *no creep* feature extends circuit life by protecting components longer and by eliminating premature failure of adjacent components caused by migrating silicone base fluid.

## The Non-Silicone Advantage

Silicone-based compounds have an undesirable tendency to physically migrate and contaminate components nearby. This interferes with circuit operation long after hardware installation to cause unexpected, untimely and often inaccessible problems. The AOS Heat Sink Compound's *no creep* feature extends circuit life by protecting components longer and by eliminating premature failure of adjacent components caused by migrating silicone base fluid.

## Product Features & Benefits

No creep extends OEM service life; compatible with metal and plastic components; no solder bath contamination; very low bleed and evaporation; 5 year minimum shelf life; excellent thermal conductivity and thermal resistance; wide operating range; meets KS 21343 spec and Military Specification MIL-C-47113B; will not dry, harden or melt in normal use; easy to apply and clean-up; safe to use.

## Major Applications

Mounting semiconductor devices; mounting power transistors and diodes; coupling entire heat generating assemblies to chassis; heat transfer medium on ballast; thermal joints; thermocouple wells; mounting power resistors; and for any device where efficient cooling is required. Major industries served include electronic (computer, appliance, wireless, etc.), automotive, and electrical.

## Typical Properties

<u>Property</u>	<u>Value</u>	<u>Test Method</u>
<b>Specific Gravity, @ 25°C</b>	2.7	ASTM D-70
<b>Bleed, @ 200°C, 24 Hrs., %/Wt</b>	0.1 %	FTM-321 MODIFIED
<b>Viscosity, 1 sec<sup>-1</sup>, 25°C/50°C</b>	470,000/407,000 cP	ARES G-2 RHEOMETER
<b>Evaporation, @ 200°C, 24 Hrs., %/Wt.</b>	0.6 %	FTM-321 MODIFIED
<b>Thermal Conductivity, @ 36°C</b>	0.82 W/m-K	ASTMD 5470-06
<b>Thermal Resistance, @ 50°C</b>	N/A	Oracle TTV Model 270-7806-01
<b>Electrical Properties</b>		
Dielectric strength, 0.05" gap, V/mil	305	ASTM D-149
Dielectric constant, 25°C @ 1,000 Hz	4.50	ASTM D-150
Dissipation factor, 25°C @ 1,000 Hz	0.0029	ASTM D-150
Volume Resistivity, ohm-cm	$1.65 \times 10^{14}$	ASTM D-257
<b>Operating Temperature Range</b>	-40°C to 180°C	
<b>Flow Rate</b>	9 to 15 g/min	AOS Method
<b>Appearance</b>	Smooth, Off-White Paste	
<b>Shelf Life</b>	5 Years	

Customers are responsible for testing AOS Thermal Compounds materials for their proposed use. Any information furnished by AOS Thermal Compounds and its agents is believed to be reliable, but AOS Thermal Compounds does not guarantee the results to be accurate and makes no warranties as to the fitness, merchantability, or suitability of any AOS material or product for any specific or general use and shall not be held liable for incidental or consequential damages of any kind. (040206)